

## Claims

1. A mold releasing film for printed circuit board production, which comprises a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more.

2. The mold releasing film for printed circuit board production according to claim 1, wherein the resin layer (P) further contains (B) a liquid crystalline polyester in an amount of 0.5 to 50 parts by weight per 100 parts by weight of the total weight of components (A) and (B).

3. The mold releasing film for printed circuit board production according to claim 2, wherein the resin layer (P) further contains (C) a compound containing monovalent, divalent, trivalent or tetravalent metal element, in an amount of 0.1 to 10 parts by weight per 100 parts by weight of the total weight of components (A) and (B).

4. The mold releasing film for printed circuit board production according to claim 3, wherein the monovalent, divalent, trivalent or tetravalent metal

element comprises at least one of a Zn element and Mg element.

5           5.   The mold releasing film for printed circuit board production according to claim 2, wherein the resin layer (P) further contains (D) a silane compound in an amount of 0.1 to 5 parts by weight per 100 parts by weight of the total weight of components (A) and (B).

10           6.   The mold releasing film for printed circuit board production according to claim 5, wherein the silane compound (D) has an amino group.

15           7.   The mold releasing film for printed circuit board production according to claim 6, wherein the resin layer (P) further contains (E) a hydrocarbon-based wax in an amount of 0.1 to 4 parts by weight per 100 parts by weight of the total weight of components (A) and (B).

20           8.   The mold releasing film for printed circuit board production according to claim 1, which has a monolayer structure consisting essentially of the resin layer (P).

9. The mold releasing film for printed circuit board production according to claim 1, which has a multilayer structure comprising the resin layer (P) and a layer (Q) containing (F) an elastomer.

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10. The mold releasing film for printed circuit board production according to claim 9, wherein the elastomer (F) is (G) a partially hydrogenated polymer of a block copolymer of an aromatic vinyl compound and a conjugated diene compound.

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11. The mold releasing film for printed circuit board production according to claim 10, wherein the content of a bonded aromatic vinyl compound in component (G) is from 5 wt% to 65 wt%.

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12. The mold releasing film for printed circuit board production according to claim 9, wherein the elastomer (F) is (H) a copolymer of ethylene and a vinyl ester compound.

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13. The mold releasing film for printed circuit board production according to any one of claims 1 to 12, obtained by molding through an extrusion tubular method.

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14. The mold releasing film for printed circuit board production according to any one of claims 1 to 12, obtained by molding through a T-die extrusion method.

5           15. The mold releasing film for printed circuit board production according to any one of claims 1 to 12, having a contact angle between the film surface of its outermost surface layer and a water drop of 80° or more.

10           16. The mold releasing film for printed circuit board production according to any one of claims 1 to 12, wherein the printed circuit board is a flexible printed circuit board.

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